

ABSTRACT**A METHOD FOR PRINTING SOLDER ONTO A WAFER AND SYSTEM
THEREOF**

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The present invention discloses a method for printing solder onto a wafer (101) comprising the steps of depositing solder paste (102) onto a wafer (101), applying an inline reflow process to the deposited solder paste (102) to form solder bumps (103) on the wafer (101), and cleaning the reflowed solder bumps (103). The method for printing
10 solder onto the wafer (101) is based on a system thereof which comprises a wafer solder printer (1), an inline reflow means (2) and a de-fluxing means (3), wherein each step has its parameters optimized by means of a staging process control.

15 *(The most illustrative figure: FIG. 1)*

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